

L Number	Hits	Search Text	DB	Time stamp
1	52835	"polymeric polyimide polymer polyimide) near4 substrate"	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/24 09:13
2	502	"(polymeric polyimide polymer polyimide) near4 substrate" and trace near4 substrate)	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/24 09:14
3	169	"(polymeric polyimide polymer polyimide) near4 substrate; and (trace near4 substrate), and 257/96.ccls."	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/24 09:27
4	82	((polymeric polyimide polymer polyimide) near4 substrate) and (trace near4 substrate)) and (MCM (multi-chip near module) (multi near chip near module))	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/24 09:46
5	21442	Yoshimura.in.	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/24 09:46
6	1810	Yoshimura.in. and optical	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/24 09:47
7	40	(Yoshimura.in. and optical) and polymeric	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/24 09:47
-	36	(polymeric polyimide polymer polyimide) same (routing route) same trace same (chip die)	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 10:46
-	426	"routing element"	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 10:51
-	20	("routing element" and (chip die)) and trace	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 10:52
-	117	"routing element" and (chip die)	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 10:56
-	97	("routing element" and (chip die)) not (("routing element" and (chip die)) and trace)	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 11:01
-	2679	257/623	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 11:01
-	1811	257/686	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 11:01
-	888	257/681	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 11:01
-	1713	257/617	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 11:01
-	1710	257/614	USPAT; US-PGPUB; EPO; JPO; DEFWENT	2003/02/13 11:01

1946	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:12
2047	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:12
1507	257/691	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:12
9386	257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:12
2629	257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691; and (polymeric polyimide polyimide polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:13
846	((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer); and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:13
258	((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer); and trace) and (route routing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:19
115	((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)) and (trace) and (route routing)) and (bond near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:25
3	"6420789"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:46
0	"6582018"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:50
13	perschelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
0	perschelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
0	perschelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
41c	"routing element"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:14
14	"routing element" and substrate and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:17
1111	substrate near trace and bond near pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:17
1111	substrate near trace and bond near pad and tiny die semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:17

54949	"wiring board"	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
3164	"wiring board" and carrier	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
431	"wiring board" and carrier and trace rout\$3	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
136	"wiring board" and carrier, and (trace rout\$3), and (bond near pad)	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
9327	((multi near chip) multichip) near5 module	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/20 09:11
1026	multi near chip; multichip; near5 module and trace and (chip die (semiconductor near device))	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/20 09:13
617	((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/20 10:54
422	(((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polyimide polym\$4 polyim\$4)	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/20 10:56
404	(((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polyimide polym\$4 polyim\$4) and substrate	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/20 11:23
116	(((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polyimide polym\$4 polyim\$4) and substrate) and rout\$4	USPAT; US-EGPUB; EPO; JPO; DERWENT	2003/02/20 11:24